

New Products

“Chip-stack WABE package” is embedded die substrate with stacking multiple ICs in vertically into multilayer FPC and has realized 400 um substrate thickness in case of embedding 2 dies vertically.

This technology gains an excellent reputation for electronics miniaturization and received the 2018 Technology Award from The Japan Institute of Electronics Packaging (JIEP).

Mass production of two chip-stack type WABE package started from 2018 and have shipped more than 1 million units in medical field. Also, according to increase demand of further miniaturization, development of three chip-stack type WABE package has been completed and sample shipment has started.

Fujikura will continue to contribute to society through the miniaturization of electronic circuits.

(Kazu ITOI, Senior Manager, Engineering Group, Medical Business Development Department)

Chip-stack WABE Package®

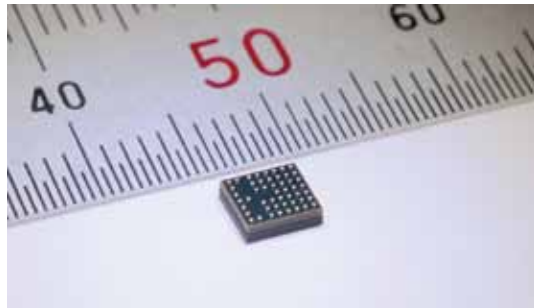


Fig. 1. IC embedding module by using chip-stack WABE Package®

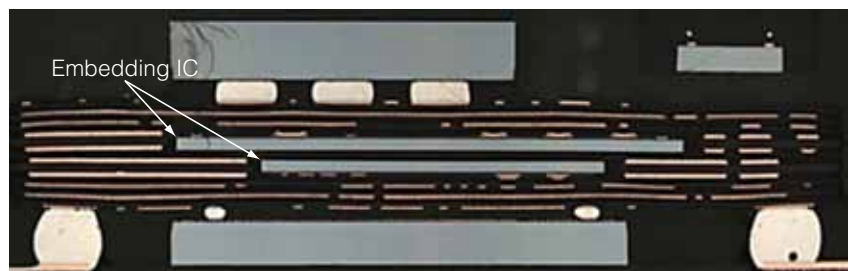


Fig. 2. Cross section of chip-stack WABE Package ®

[Information]
Medical Business Development Department
TEL : +81-3-5606-1208
E-mail : medical@jp.fujikura.com